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AMENDMENTS TO THE SPECIFICATION

In the Title:

Please replace the Title with the following Title:

--ELECTRONIC DEVICE WITH REDUCED ENTRAPMENT OF MATERIAL
BETWEEN DIE AND SUBSTRATE ELECTRICAL CONNECTIONS AND
METHOD FOR MANUFACTURE THEREOF--

In the Specification:

Please replace paragraph 16 with the following rewritten paragraph:

-- [0016] Fig. 1A is a cutaway view of a chip package according to one embodiment of the present invention. Referring to Fig. 1A, package 10 includes a heat spreader 20, an electrical unit such as, for example, a substrate 30, and an electrical unit such as, for example, a die 40, which may be a semiconductor die. A material or structure such as thermal interface material 25 may be placed between heat spreader 20 and die 40. Die 40 may be, for example, a processing, memory or other electronic chip or device. Thermal interface material 25 and heat spreader 20 need not be used. Substrate 30 provides structural strength for the package 10, and provide external electrical connections for die 40. Substrate 30 includes external electrical connections such as, for example, pins 32, providing external electrical connections. For example, pins 32 may connect to sockets in a circuit board. Connections other than pins may be used. Pins 30 32 connect to internal electrical connections 34 inside substrate 30 which in turn connect to electrical contacts or bumps 36, possibly via pads or other electrical connections 35 on the surface of substrate 30. Combinations of components such as, for example, pins 30 32, internal electrical connections 34, pads or other electrical connections 35 and bumps 36 may be formed from one piece of material. Furthermore, other systems and structures for forming electrical connections on a substrate, or support device in a package may be used. While a certain number of pins and bumps are shown in Fig. 1A, other numbers may be used. Bumps 36 may have other shapes and structures. Other structures or components, such as sealant, may be used. --